



Temperature and time recommendations

Tin-Nickel Plating using Pb free solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Gold Plating using Pb free solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Tin-Nickel Plating using Pb solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 245°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Gold Plating using Pb solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 235°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Tin Plating using Pb free solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Silver Plating using Pb free solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 260°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Tin Plating using Pb solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 235°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Silver Plating using Pb solder	
Average Ramp Up Rate	~3°C/Sec.
Preheat - Temperature 150°C to 200°C	60-180 Sec
Critical Temperature - 217°C	60-150 sec
Peak temperature - 235°C	20-40 sec
Average Ramp Down Rate	~6°C/Sec

Disclaimer

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